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Response Under 37 C.F.R. 1.116 (After Final)  
Expedited Procedure Examining Group 2827

Attorney Docket: KAM/133/PC/US

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Application No. 09/786,597  
Applicant(s): Kenichi Hirahara et al.  
Filing Date: February 28, 2001  
Title: Through Hole Conduction Structure of Flexible  
Multilayer Circuit Board and Forming Method  
Thereof  
Group/Art Unit 2827  
Examiner: Tuan T. DINH

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

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TECHNICAL CENTER 2827

**Response to Final Office Action Under 37 C.F.R. 1.116**

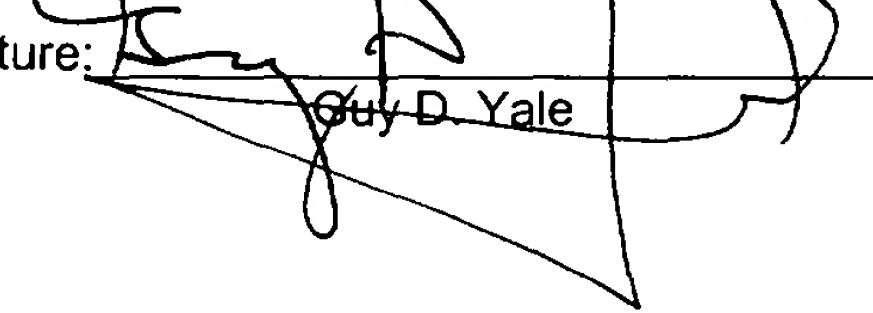
Sir:

This amendment is being made under 37 C.F.R. §1.116. In response to the Office Action of July 7, 2003 please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Mailing Certificate**

I hereby certify that this correspondence is being deposited on the date given below with the United States Post Office Service as First Class mail in an envelope addressed to:  
Mail Stop AF Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Signature:   
Guy D. Yale

Reg. No.: 29,125 Date: September 9, 2003